FEATURES:

- **0.5 MICRON CMOS Technology**
- **Typical $t_{SK(o)}$ (Output Skew) < 250ps**
- **ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)**
- **V_{CC} = 3.3V ± 0.3V, Normal Range, or V_{CC} = 2.7V to 3.6V, Extended Range**
- **CMOS power levels (0.4µ W typ. static)**
- **Rail-to-rail output swing for increased noise margin**
- **Low Ground Bounce (0.3V typ.)**
- **Inputs (except I/O) can be driven by 3.3V or 5V components**
- **Available in TSSOP package**

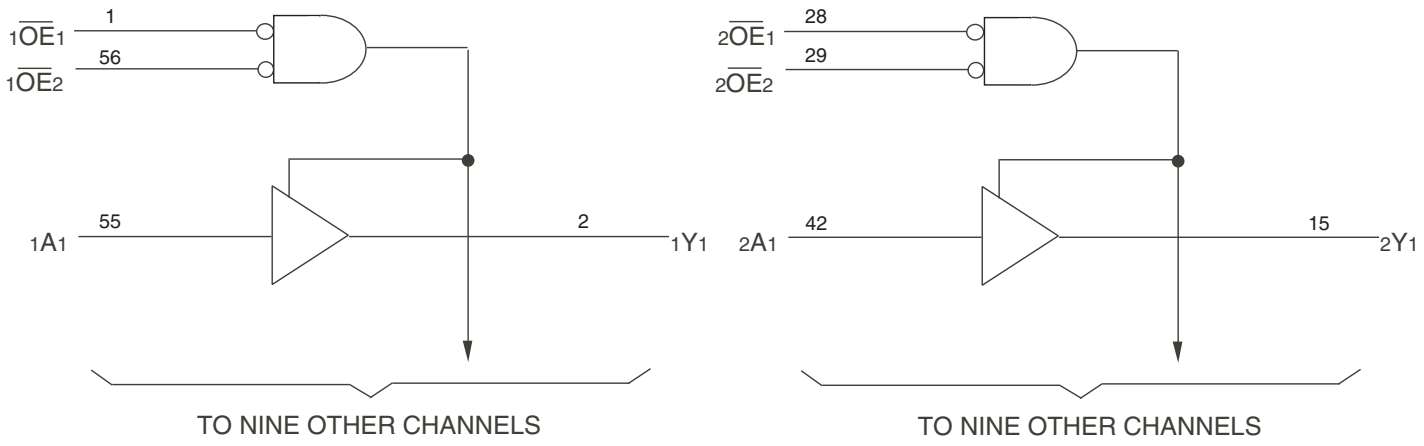
DESCRIPTION:

The FCT163827 20-bit buffer is built using advanced dual metal CMOS technology. These 20-bit bus drivers provide high-performance bus interface buffering for wide data/address paths or busses carrying parity. Two pairs of NAND-ed output enable controls offer maximum control flexibility and are organized to operate the device as two 10-bit buffers or one 20-bit buffer. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

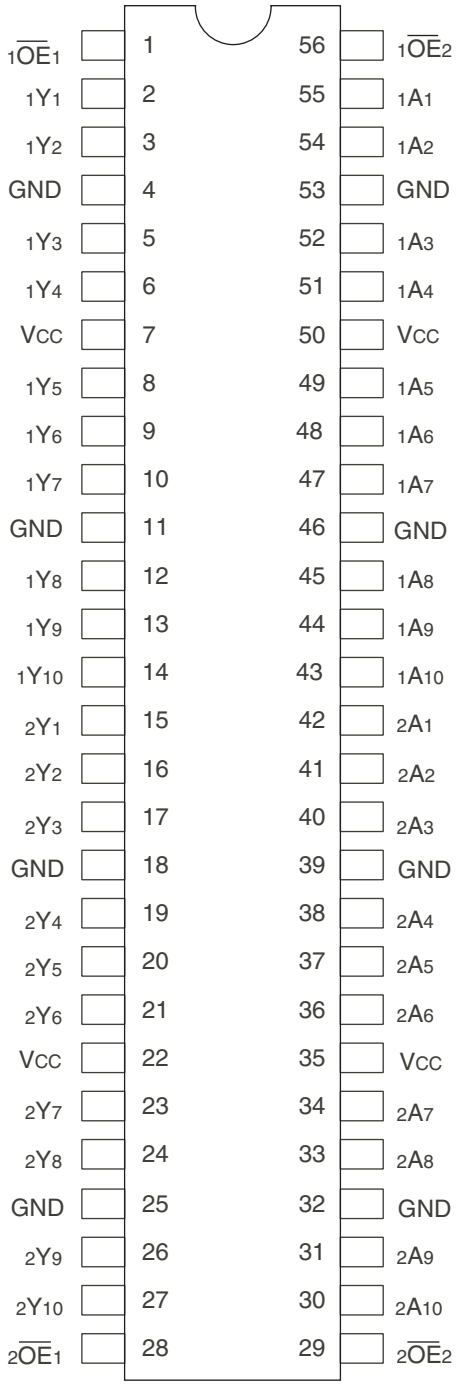
The FCT163827 has series current limiting resistors. This offers low ground bounce, minimal undershoot, and controlled output fall times, reducing the need for external series terminating resistors.

The inputs of the FCT163827 can be driven from either 3.3V or 5V devices. This feature allows the use of these devices as translators in a mixed 3.3V/5V supply system.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



TOP VIEW

Package Type	Package Code	Order Code
TSSOP	PAG56	PAG

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
V_{TERM}(2)	Terminal Voltage with Respect to GND	–0.5 to +4.6	V
V_{TERM}(3)	Terminal Voltage with Respect to GND	–0.5 to 7	V
V_{TERM}(4)	Terminal Voltage with Respect to GND	–0.5 to V_{CC}+0.5	V
T_{STG}	Storage Temperature	–65 to +150	°C
I_{OUT}	DC Output Current	–60 to +60	mA

NOTES:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. Vcc terminals.
3. Input terminals.
4. Outputs and I/O terminals.

CAPACITANCE (T_A = +25°C, F = 1.0MHz)

Symbol	Parameter(1)	Conditions	Typ.	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	3.5	6	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V	3.5	8	pF

NOTE:
1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
x$\overline{OE}$x	Output Enable Inputs (Active LOW)
xAx	Data Inputs
xYx	3-State Outputs

FUNCTION TABLE(1)

Inputs			Outputs
x$\overline{OE}_1$	x$\overline{OE}_2$	xAx	xYx
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

NOTE:
1. H = HIGH Voltage Level
   L = LOW Voltage Level
   X = Don't Care
   Z = High-impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:
Industrial: T_A = –40°C to +85°C, V_{CC} = 2.7V to 3.6V

Symbol	Parameter	Test Conditions[1]		Min.	Typ.[2]	Max.	Unit
V_{IH}	Input HIGH Level (Input pins)	Guaranteed Logic HIGH Level		2	—	5.5	V
	Input HIGH Level (I/O pins)			2	—	V_{CC}+0.5	
V_{IL}	Input LOW Level (Input and I/O pins)	Guaranteed Logic LOW Level		–0.5	—	0.8	V
I_{IH}	Input HIGH Current (Input pins)	V_{CC} = Max.	V_I = 5.5V	—	—	±1	µA
	Input HIGH Current (I/O pins)		V_I = V_{CC}	—	—	±1	
I_{IL}	Input LOW Current (Input pins)		V_I = GND	—	—	±1	
	Input LOW Current (I/O pins)		V_I = GND	—	—	±1	
I_{OZH}	High Impedance Output Current	V_{CC} = Max.	V_O = V_{CC}	—	—	±1	µA
I_{OZL}	(3-State Output pins)		V_O = GND	—	—	±1	
V_{IK}	Clamp Diode Voltage	V_{CC} = Min., I_{IN} = –18mA		—	–0.7	–1.2	V
I_{ODH}	Output HIGH Current	V_{CC} = 3.3V, V_{IN} = V_{IH} or V_{IL}, V_O = 1.5V[3]		–36	–60	–110	mA
I_{ODL}	Output LOW Current	V_{CC} = 3.3V, V_{IN} = V_{IH} or V_{IL}, V_O = 1.5V[3]		50	90	200	mA
V_{OH}	Output HIGH Voltage	V_{CC} = Min.	I_{OH} = –0.1mA	V_{CC}-0.2	—	—	V
		V_{IN} = V_{IH} or V_{IL}	I_{OH} = –3mA	2.4	3	—	
		V_{CC} = 3V V_{IN} = V_{IH} or V_{IL}	I_{OH} = –8mA	2.4[5]	3	—	
V_{OL}	Output LOW Voltage	V_{CC} = Min.	I_{OL} = 0.1mA	—	—	0.2	V
		V_{IN} = V_{IH} or V_{IL}	I_{OL} = 16mA	—	0.2	0.4	
			I_{OL} = 24mA	—	0.3	0.55	
		V_{CC} = 3V V_{IN} = V_{IH} or V_{IL}	I_{OL} = 24mA	—	0.3	0.5	
I_{OS}	Short Circuit Current[4]	V_{CC} = Max., V_O = GND[3]		–60	–135	–240	mA
V_H	Input Hysteresis	—		—	150	—	mV
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	V_{CC} = Max. V_{IN} = GND or V_{CC}		—	0.1	10	µA

NOTES:
1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at V_{CC} = 3.3V, +25°C ambient.
3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
4. This parameter is guaranteed but not tested.
5. V_{OH} = V_{CC}–0.6V at rated current.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions[1]		Min.	Typ.[2]	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V_{CC} = Max. V_{IN} = V_{CC} - 0.6V[3]		—	2	30	µA
I_{CCD}	Dynamic Power Supply Current[4]	V_{CC} = Max. Outputs Open $x\overline{OE}_1$ = $x\overline{OE}_2$ = GND One Input Toggling 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	—	50	75	µA/ MHz
I_C	Total Power Supply Current[6]	V_{CC} = Max.,Outputs Open f_I = 10MHz 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	—	0.5	0.7	mA
		$x\overline{OE}_1$ = $x\overline{OE}_2$ = GND One Bit Toggling	V_{IN} = V_{CC} - 0.6V V_{IN} = GND	—	0.5	0.8	
		V_{CC} = Max.,Outputs Open f_I = 2.5MHz 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	—	2.5	3.7[5]	
		$x\overline{OE}_1$ = $x\overline{OE}_2$ = GND Twenty Bits Toggling	V_{IN} = V_{CC} - 0.6V V_{IN} = GND	—	2.5	4.1[5]	

NOTES:

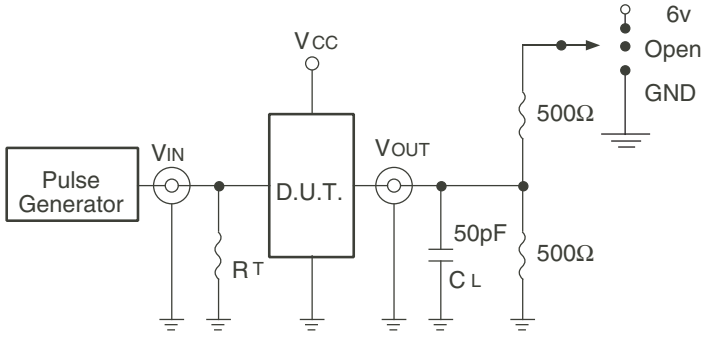
1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at V_{CC} = 3.3V, +25°C ambient.
3. Per TTL driven input. All other inputs at V_{CC} or GND.
4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
5. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
   $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP} N_{CP}/2 + f_i N_i)$
   I_{CC} = Quiescent Current (I_{CCL}, I_{CCH} and I_{CCZ})
   ΔI_{CC} = Power Supply Current for a TTL High Input
   D_H = Duty Cycle for TTL Inputs High
   N_T = Number of TTL Inputs at D_H
   I_{CCD} = Dynamic Current caused by an Input Transition Pair (HLH or LHL)
   f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)
   N_{CP} = Number of Clock Inputs at f_{CP}
   f_i = Input Frequency
   N_i = Number of Inputs at f_i

SWITCHING CHARACTERISTICS OVER OPERATING RANGE[1]

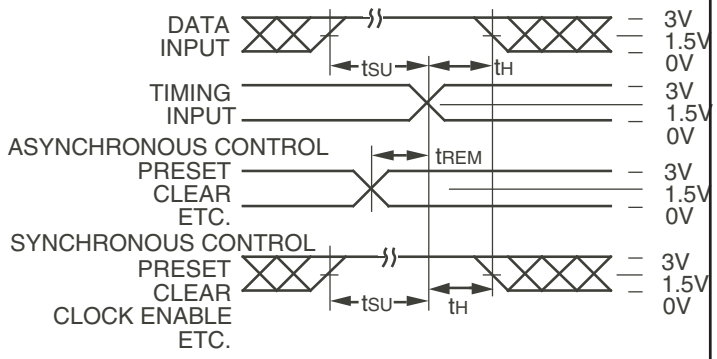
Symbol	Parameter	Condition[2]	FCT163827A		FCT163827C		Unit
			Min.[3]	Max.	Min.[3]	Max.	
t_{PLH} t_{PHL}	Propagation Delay xAx to xYx	C_L = 50pF R_L = 500Ω	1.5	8	1.5	4.4	ns
		C_L = 300pF[4] R_L = 500Ω	1.5	15	1.5	10	
t_{PZH} t_{PZL}	Output Enable Time x$\overline{OE}$x to xYx	C_L = 50pF R_L = 500Ω	1.5	12	1.5	7	ns
		C_L = 300pF[4] R_L = 500Ω	1.5	23	1.5	14	
t_{PHZ} t_{PLZ}	Output Disable Time x$\overline{OE}$x to xYx	C_L = 5pF[4] R_L = 500Ω	1.5	9	1.5	5.7	ns
		C_L = 50pF R_L = 500Ω	1.5	10	1.5	6	
$t_{SK(o)}$	Output Skew[3]		—	0.5	—	0.5	ns

NOTES:
1. See test circuit and waveforms.
2. Minimum limits are guaranteed but not tested.
3. Skew between any two outputs, of the same package, switching in the same direction. This parameter is guaranteed by design.
4. Propagation Delays and Enable/Disable times are with V_{CC} = 3.3V ±0.3V, Normal Range. For V_{CC} = 2.7V to 3.6V, Extended Range, all Propagation Delays and Enable/Disable times should be degraded by 20%.

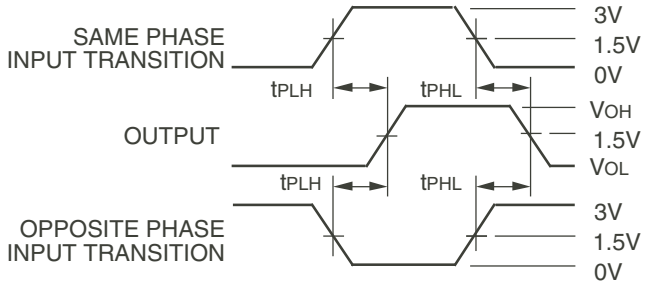
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



Propagation Delay

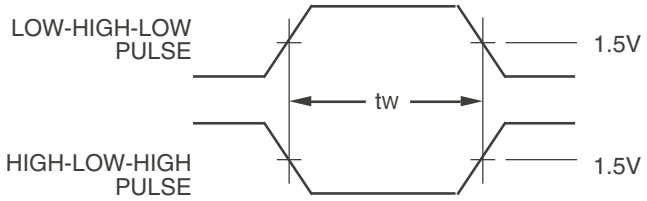
SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	6V
Disable High Enable High	GND
All Other Tests	Open

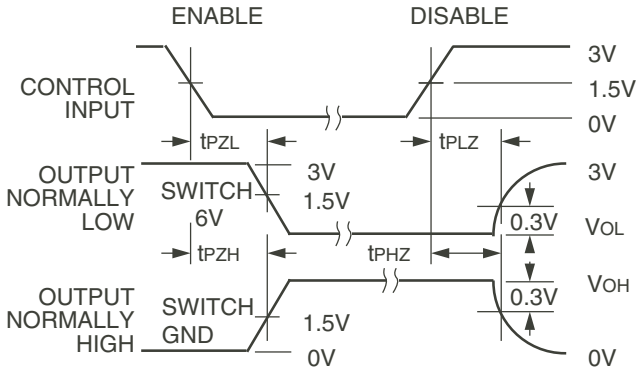
DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.



Pulse Width

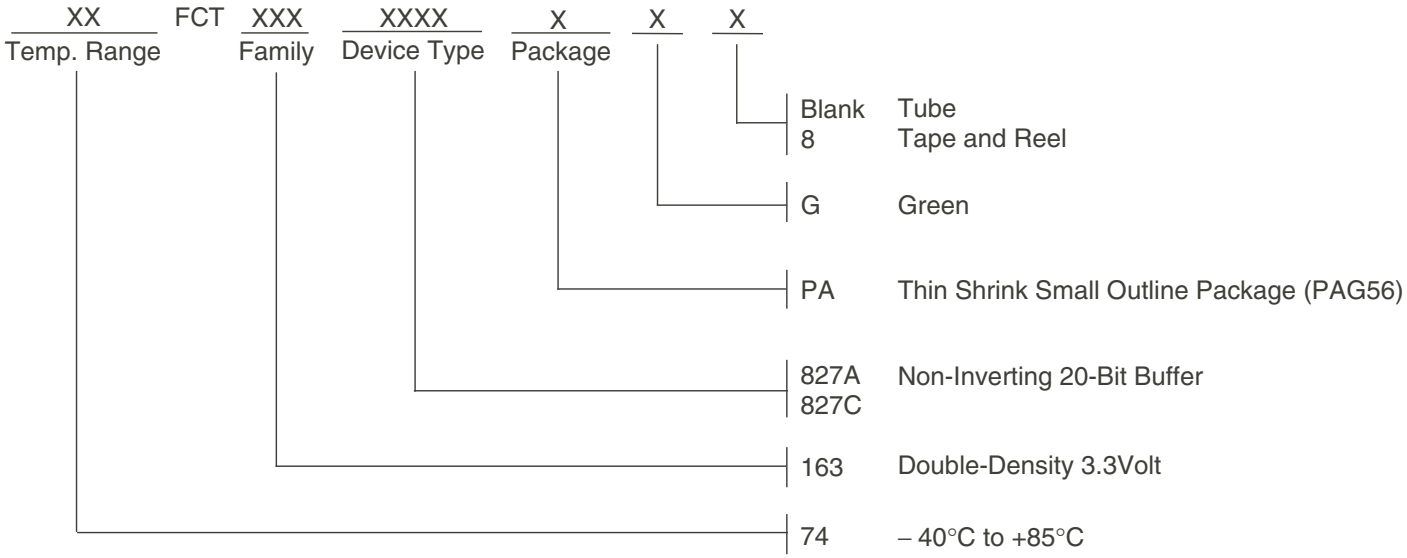


Enable and Disable Times

NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
3. if V_{CC} is below 3V, input voltage swings should be adjusted not to exceed V_{CC}.

ORDERING INFORMATION



Orderable Part Information

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
A	74FCT163827APAG	PAG56	TSSOP	I
	74FCT163827APAG8	PAG56	TSSOP	I
C	74FCT163827CPAG	PAG56	TSSOP	I
	74FCT163827CPAG8	PAG56	TSSOP	I

Datasheet Document History

09/28/2009	Pg. 7	Updated the ordering information by removing the "IDT" notation and non RoHS part.
05/10/2018	Pg. 1, 2, 5, 7	Added table under pin configuration diagram with detailed package information. Updated the ordering information diagram adding Tube, Tape and Reel. Added orderable part information table.
05/06/2019	Pg. 7	Corrected package count in ordering information diagram.

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